

Tab settings ⇄ ⇄ ⇄ ▼



To the Honorable Commissioner of Pat

100913656

ached original documents or copy thereof.

56-68-102w

1. Name of conveying party(ies):

John H. Lau, Tzyy Jang Tseng, and  
Chen-Hua Cheng

Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other \_\_\_\_\_

Execution Date: September 26, 1998

2. Name and address of receiving party(ies):

Name: Express Packaging Systems, Inc.

Internal Address: \_\_\_\_\_

Street Address: 1137-B San Antonio Road

City: Palo Alto State: CA ZIP: 94303

Additional name(s) & address(es) attached?  Yes  No

JCS 549 U.S. PTO  
09/200691  
11/27/98

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: September 26, 1998

A. Patent Application No.(s)

09/200691

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Bo-In Lin

Internal Address: \_\_\_\_\_

Street Address: 13445 Mandoli Drive

City: Los Altos Hills State: CA ZIP: 94022

6. Total number of applications and patents involved: One

7. Total fee (37 CFR 3.41):..... \$ 40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number: \_\_\_\_\_

(Attach duplicate copy of this page if paying by deposit account)

12/04/1998 BMSUYEN 00000215 09200691

DO NOT USE THIS SPACE

01 FC:581

40.00 DP

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ching-lu Lin

Name of Person Signing

Ching-lu Lin

Signature

Nov. 27, 1998

Date

Total number of pages comprising cover sheet

Four

## ASSIGNMENT

INVENTOR

Whereas, I, John H. Lau of 961 Newell Road, Palo Alto,  
California 94303,  
have invented:

TITLE:

A HEAT SPREADER WITH A PLACEMENT RECESS AND BOTTOM  
SAW-TEETH FOR CONNECTION TO GROUND COPLANAR STRIPS ON  
A THIN TWO-SIDED SINGLE-CORE BGA SUBSTRATE

DATE INVENTOR  
SIGNED THE  
DECLARATION

and executed a United States patent application therefor  
on Sept. 26, 1998;

Whereas, Express Packaging Systems, Inc. having a place  
of business at Palo Alto, California, (hereinafter called EPS),  
desires to acquire the entire right, title and interest of said  
application and invention, and to any United States and foreign  
patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt  
whereof is hereby acknowledged, I, the above named, hereby sell,  
assign, and transfer to EPS, its successors and assigns, the entire  
right, title and interest in the said application and invention  
therein disclosed for the United States and foreign countries, and  
all rights of priority resulting from the filing said United States  
application, and I request the Commissioner of Patents to issue  
any Letters Patent granted upon the inventions set forth in said  
application to EPS its successors and assigns; and I hereby agree  
that EPS may apply for foreign Letters Patent on said invention  
and I will execute all papers necessary in connection with the  
United States and foreign applications when called upon to do so  
by

CITY AND  
DATE

Signed and Sealed at Palo Alto  
on Sept. 26, 1998.

John H. Lau

-----  
SIGNATURE OF INVENTOR

Docket No. EPS-9701

**ASSIGNMENT**

**INVENTOR  
AND CITY**

Whereas, I, Tzyy Jang Tseng of No. 36, Hu-pin Second Road,  
Science-Based Park, Hsinchu, Taiwan, R. O. C.

have invented:

**TITLE:**

**A HEAT SPREADER WITH A PLACEMENT RECESS AND BOTTOM  
SAW-TEETH FOR CONNECTION TO GROUND COPLANAR STRIPS ON  
A THIN TWO-SIDED SINGLE-CORE BGA SUBSTRATE**

**DATE INVENTOR  
SIGNED THE  
DECLARATION**

and executed a United States patent application therefor

on Sept. 26/, 1998;

Whereas, World Wiser Electronics, Inc. having a place of  
business at Taoyuan Hsien, Taiwan, R. O. C., (hereinafter called  
World Wiser), desires to acquire the entire right, title and interest  
of said application and invention, and to any United States and  
foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt  
whereof is hereby acknowledged, I, the above named, hereby sell,  
assign, and transfer to World Wiser, its successors and assigns,  
the entire right, title and interest in the said application and  
invention therein disclosed for the United States and foreign  
countries, and all rights of priority resulting from the filing said  
United States application, and I request the Commissioner of  
Patents to issue any Letters Patent granted upon the inventions  
set forth in said application to World Wiser its successors and  
assigns; and I hereby agree that World Wiser may apply for  
foreign Letters Patent on said invention and I will execute all  
papers necessary in connection with the United States and  
foreign applications when called upon to do so by

**CITY AND  
DATE**

Signed and Sealed at TAO-YUAN, TAIWAN  
on Sept. 26, 1998.

Tzyy - Jang Tseng  
SIGNATURE OF INVENTOR

Docket No. EPS-9701

**ASSIGNMENT**

**INVENTOR  
AND CITY**

Whereas, I, **Chen-Hua Cheng** of 5F-2, No.110, West Kang Road,  
7 Lin, Chin-Hsia Village, Lu-Chu County, Taoyuan Hsien,  
Taiwan, R. O. C.

have invented:

**TITLE:**

**A HEAT SPREADER WITH A PLACEMENT RECESS AND BOTTOM  
SAW-TEETH FOR CONNECTION TO GROUND COPLANAR STRIPS ON  
A THIN TWO-SIDED SINGLE-CORE BGA SUBSTRATE**

**DATE INVENTOR  
SIGNED THE  
DECLARATION**

and executed a United States patent application therefor  
on Sept 26, 1998;

Whereas, World Wiser Electronics, Inc. having a place of  
business at Taoyuan Hsien, Taiwan, R. O. C., (hereinafter called  
World Wiser), desires to acquire the entire right, title and interest  
of said application and invention, and to any United States and  
foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt  
whereof is hereby acknowledged, I, the above named, hereby sell,  
assign, and transfer to World Wiser, its successors and assigns,  
the entire right, title and interest in the said application and  
invention therein disclosed for the United States and foreign  
countries, and all rights of priority resulting from the filing said  
United States application, and I request the Commissioner of  
Patents to issue any Letters Patent granted upon the inventions  
set forth in said application to World Wiser its successors and  
assigns; and I hereby agree that World Wiser may apply for  
foreign Letters Patent on said invention and I will execute all  
papers necessary in connection with the United States and  
foreign applications when called upon to do so by

**CITY AND  
DATE**

Signed and Sealed at TAOYUAN TAIWAN  
on Sept 26, 1998.

Chen-Hua Cheng  
SIGNATURE OF INVENTOR